

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HYMITE A/S	08/09/2010
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
Street Address:	No. 8, Li-Hsin Rd. 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 15	
Property Type	Number
Patent Number:	7057274
Patent Number:	7081412
Application Number:	60329699
Application Number:	60457435
Application Number:	60565217
Application Number:	60576765
Application Number:	60609284
Application Number:	60662644
Application Number:	60717818
Application Number:	60735485
Application Number:	60737532
Application Number:	60749247
Application Number:	60848043
Application Number:	61144525

501652083

PATENT
REEL: 026875 FRAME: 0305

OP \$600.00 7057274

Application Number: 61152382

CORRESPONDENCE DATA

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Address Line 4: Dallas, TEXAS 75219

ATTORNEY DOCKET NUMBER:	24061.1636 (HYMITE-TSMC)
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NAME OF SUBMITTER:	David M. O'Dell
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Total Attachments: 11

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ASSIGNMENT OF PATENTS

This Assignment of Patents ("**Assignment**") is made and entered into on this 10th day of August, 2010, by and between:

Hymite A/S, a Danish company, with offices at Gydevang 39-41, Bldg. E0, 3450 Allerød, Denmark ("**ASSIGNOR**"); and

Taiwan Semiconductor Manufacturing Company, Ltd., a(n) company duly incorporated under the laws of the Republic of China, having its principle place of business at No. 8, Li-Hsin Rd. 6, Hsin-Chu Science Park, Hsin-Chu, Taiwan 300-77, the Republic of China ("**ASSIGNEE**").

WHEREAS, ASSIGNOR has agreed to assign and transfer to ASSIGNEE all right, title and interest in and to the Assigned Patents (as defined below).

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, ASSIGNOR, intending to be legally bound, and upon the terms set forth herein, agrees as follows:

ASSIGNOR does hereby irrevocably assign, sell, transfer and set over to ASSIGNEE its entire right, title and interest in, to and under the patents and patent applications set forth on **Attachment A** attached hereto, including any and all letters patents issuing from any continuing, divisional and continuation-in-part applications; any requests for continuing examination, substitutions, reissues, extensions, renewals and reexaminations of any of the foregoing; all inventions and discoveries described in any of the foregoing; and all rights to apply in any country for any foreign counterpart, certification of invention or other governmental grant or issuance corresponding to any of the foregoing throughout the world (collectively, the "**Assigned Patents**"), including any and all past, present and future causes of action and other enforcement actions (including, without limitation, for injunctive remedies and relief) and rights to damages and profits, due or accrued, relating to any of the foregoing, including the right to sue and recover for, and the right to profits and damages, due or accrued, arising out of or in connection with, any and all past, present or future infringements or dilutions.

ASSIGNOR agrees for itself and its successors, legal representatives and assigns, without further compensation, to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the ASSIGNEE may reasonably request to effectuate fully this assignment.

IN WITNESS WHEREOF, ASSIGNOR has caused this Assignment of Patents to be



executed by its duly authorized representative on the date set forth below.

ASSIGNOR:

Hymite A/S

Entity Name

By: 

Printed Name: Sten Larsen

Title (if applicable): CEO



On this 9 day of August 2010, before me, a Notary Public, appeared _____, who is personally known to me or proved to me on the basis of satisfactory evidence to be the same person whose name is subscribed to this Assignment document.

Witness my hand and official seal:

Notary Public



Eva Olesen



Grunddata: 285600 02 0000.0012 09.08.2010 RG
69100-00437/2010 300+00 *







This is to certify that Mr. Sten Larsen today in my presence at the Notarial Office approved and signed the above document. No conspicuous corrections or addenda were found in the document.

Mr. Sten Larsen has proved his identity by showing his passport.

The Court in Hillerød, Denmark, 9th of August 2010

Eva Olesen
Notary Public



ATTACHMENT A

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
DOUBLE-SIDED ETCHING TECHNIQUE FOR PROVIDING A SEMICONDUCTOR STRUCTURE WITH THROUGH-HOLES, AND A FEED-THROUGH METALIZATION PROCESS FOR SEALING THE THROUGH-HOLES						
Matthias Heschel						
	UNITED STATES	FCA	2002/10/4	10/264,440	2004/11/16	6,818,464
	UNITED STATES	DIV	2004/7/20	10/894,989	2006/6/6	7,057,274
	UNITED STATES	CON	2004/10/5	10/958,524	2006/7/25	7,081,412
	CHINA	DCA	2002/10/15	2825292.6	2008/3/26	ZL02825292.6
	GERMANY	DCA	2002/10/15	2787490.8	2010/3/18	60236007.2-08
	EUROPEAN	DCA	2002/10/15	2787490.8	2010/3/18	1436837
	HONG KONG	CEQ	2002/10/15	5107072.1	2009/2/6	HK1074913
	JAPAN	DCA	2002/10/15	2003-537117		
	UNITED STATES	NEW	2001/10/17	60/329,699		
	TAIWAN	CEQ	2001/6/11	90127456	2003/9/30	179004
	WIPO	CEQ	2002/10/15	PCT/EP02/11605		
HYBRID INTEGRATION OF ACTIVE AND PASSIVE OPTICAL COMPONENTS ON AN SI-BOARD						
Jochen Friedrich Kuhmann, Mogens Rysholt Poulsen						
	UNITED STATES	DCA	2002/4/23	10/030,639	2004/12/14	6,832,013
	AUSTRALIA	DCA	2000/7/17	59670/00		
	BRAZIL	DCA	2000/7/17	PI0012511-3		
	CANADA	DCA	2000/7/17	2378972		
	CHINA	DCA	2000/7/17	812991.6	2005/1/5	ZL00812991.6
	EUROPEAN	DCA	2000/7/17	945666.6		
	HONG KONG	CEQ	3/12/2003	3101790.7		
	ISRAEL	DCA	2000/7/17	147358		
	JAPAN	DCA	2000/7/17	2001-510866		
	SOUTH KOREA	DCA	2000/7/17	7000672/2002	2007/9/20	762387
	MEXICO	DCA	2000/7/17	2002/000466		
	POLAND	DCA	2000/7/17	DK00/00407		
	SINGAPORE	DCA	2000/7/17	200108036-5		
	WIPO	CEQ	2000/7/17	PCT/DK00/00407		

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
ACCURATE POSITIONING OF COMPONENTS OF AN OPTICAL ASSEMBLY						
Kristian Blidegn, Ph.D						
	UNITED STATES	FCA	2003/7/10	10/616,521	2007/4/24	7,209,235
	UNITED STATES	DIV	2007/3/13	11/685,494	2008/8/19	7,415,180
	UNITED STATES	NEW	2002/7/11	60/395,196		
	WIPO	CEQ	2003/7/10	PCT/IB03/03460		
ENCAPSULATED OPTICAL FIBER END-COUPLED DEVICE						
Arnd Kilian						
	UNITED STATES	NEW	2002/8/21	10/224,801	2004/9/7	6,786,654
	TAIWAN	CEQ	2002/9/12	91120812	2004/10/7	203873
	WIPO	CEQ	2003/8/20	PCT/IB03/03916		
PLANAR WAVEGUIDE COUPLING LENS						
Arnd Kilian						
	UNITED STATES	NEW	2003/3/25	60/457,435		
OPTICAL DEVICE RECEIVING SUBSTRATE AND OPTICAL DEVICE HOLDING CARRIER						
JOCHEN FRIEDRICH KUHMANN, MATTHIAS HESCHEL						
	UNITED STATES	FCA	2003/5/14	10/437,543	2007/5/8	7,213,978
	UNITED STATES	NEW	2002/5/15	60/380,287		
	TAIWAN	CEQ	2003/5/14	92113013		
	WIPO	CEQ	2003/5/13	PCT/EP03/05071		
MOUNTING OF COMPONENTS ON A SUBSTRATE						
Johech Kuhmann, Randolph Burghardt						
	GERMANY	DCA	1995/10/10	19539392.9-24		
OPTICAL PACKAGE WITH AN INTEGRATED LENS AND OPTICAL ASSEMBLIES INCORPORATING THE PACKAGE						
Arnd Kilian						
	UNITED STATES	NEW	2002/11/26	10/305,255	2005/11/29	6,969,204
	CHINA	DCA	2003/11/24	200380109124.3	2008/4/23	ZL200380109124.3
	EUROPEAN	DCA	2003/11/24	3772535.5		3
	HONG KONG	CEQ	2003/11/24	6102032		
	JAPAN	DCA	2003/11/24	2004-554839		
	TAIWAN	CEQ	2003/11/25	92132974	2007/11/21	I290245
	WIPO	CEQ	2003/11/24	PCT/IB03/05394		

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
PACKAGE WITH A LIGHT EMITTING DEVICE						
Arnd Kilian						
	UNITED STATES	NEW	2003/3/24	10/395,687	2005/2/15	6,856,717
	TAIWAN	CEQ	2004/3/23	93107695		
	WIPO	CEQ	2004/3/23	PCT/IB2004/001306		
THREE-DIMENSIONAL INDUCTIVE MICROCOMPONENTS						
Arnd Kilian, RALF HAUFFE						
	UNITED STATES	NEW	2003/11/3	10/699,981		
	TAIWAN	CEQ	2004/11/2	93133276		
	WIPO	CEQ	2004/11/1	PCT/IB2004/003582		
LIGHT TRANSMITTING MODULES WITH OPTICAL POWER MONITORING						
RALF HAUFFE, Arnd Kilian						
	UNITED STATES	NEW	2004/2/12	10/777,583	2007/1/23	7,165,896
	UNITED STATES	DIV	2006/12/4	11/566,448	2008/12/23	7,467,897
	WIPO	CEQ	2005/2/10	PCT/IB2005/000967		
MICROELECTROMECHANICAL SYSTEMS (MEMS) DEVICES INTEGRATED IN A HERMETICALLY SEALED PACKAGE						
Lior Shiv						
	UNITED STATES	FCA	2005/6/2	11/144,429		
	UNITED STATES	NEW	2004/6/3	60/576,765		
	UNITED STATES	NEW	2005/3/17	60/662,644		
	WIPO	CEQ	2005/6/3	PCT/IB2005/002286		
METHOD OF FORMING AN ASSEMBLY TO HOUSE ONE OR MORE MICRO COMPONENTS						
Matthias Heschel, Arnd Kilian						
	UNITED STATES	NEW	2004/4/28	10/833,428	2010/3/23	7,681,306
	WIPO	CEQ	2005/4/19	PCT/IB2005/001148		
HERMETICALLY SEALED PACKAGE FOR OPTICAL, ELECTRONIC, OPTO-ELECTRONIC AND OTHER DEVICES						
Matthias Heschel, Kristian Blidegn, Ph.D, Jorgen Hoeg						
	UNITED STATES	NEW	2004/3/3	10/792,529	2006/9/19	7,109,580
	UNITED STATES	DIV	2006/8/8	11/501,139	2008/6/17	7,388,285
	WIPO	CEQ	2005/2/28	PCT/US2005/006748		

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
ASSEMBLY WITH SELF-ALIGNMENT FEATURES TO POSITION A COVER ON A SUBSTRATE THAT SUPPORTS A MICRO COMPONENT						
Jochen Kuhmann, Dr. Matthias Heschel						
	UNITED STATES	FCA	2004/5/17	10/848,498	2007/8/7	7,253,388
	UNITED STATES	NEW	2004/4/23	60/565,217		
OPTICAL MODULE HERMETICALLY PACKAGED IN MICRO-MACHINED STRUCTURES						
Arnd Kilian, Ralf Hauße, Marcus Winter						
	UNITED STATES	FCA	2005/9/12	11/225,758	2009/6/9	7,543,999
	JAPAN	DCA	2005/9/12	2007-530800		
	SOUTH KOREA	DCA	2005/9/12	7008342/2007		
	UNITED STATES	NEW	2004/9/13	60/609,284		
	TAIWAN	CEQ	2005/9/12	94131374		
	WIPO	CEQ	2005/9/12	PCT/IB2005/002994		
METHOD OF FABRICATING A PACKAGE FOR A MICRO COMPONENT						
Lior Shiv, Kristian Blidegn						
	UNITED STATES	NEW	2005/3/17	11/082,507	2009/6/30	7,553,695
	CHINA	DCA	2006/3/15	200680017260.3		
	HONG KONG	CEQ	2008/11/27	8112984.5		
	JAPAN	DCA	2006/3/15	2008-501443		
	WIPO	CEQ	2006/3/15	PCT/IB2006/000661		
OPTICAL COMMUNICATION WITH WAVELENGTH SEPARATION						
Arnd Kilian						
	UNITED STATES	NEW	2006/4/24	11/410,475		
FABRICATION AND USE OF POLISHED SILICON MICRO-MIRRORS						
Lior Shiv						
	UNITED STATES	NEW	2005/6/17	11/156,170	2008/12/30	7,470,622
CHIP SCALE PACKAGE FOR A MICRO COMPONENT						
Jochen Kuhmann, Matthias Heschel						
	UNITED STATES	NEW	2005/8/11	11/202,478	2008/9/2	7,419,853
	UNITED STATES	DIV	2008/6/20	12/143,003		
	CHINA	DCA	2006/8/10	200680029469.1		
	EUROPEAN	DCA	2006/8/10	6795501.3		
	HONG KONG	CEQ	2008/10/21	8110452.2		
	JAPAN	DCA	2006/8/10	2008-525661		
	WIPO	CEQ	2006/8/10	PCT/IB2006/002555		

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
QFN/SON- COMPATIBLE PACKAGE						
Andreas Alfred Hase						
	UNITED STATES	FCA	2006/9/15	11/521,828		
	UNITED STATES	NEW	2005/9/16	60/717,818		
SEALED PACKAGE WITH GLASS WINDOW FOR OPTOELECTRONIC COMPONENTS, AND ASSEMBLIES INCORPORATING THE SAME						
Lior Shiv, Jochen Kuhmann						
	UNITED STATES	FCA	2006/11/9	11/558,175		
	UNITED STATES	NEW	2005/11/10	60/735,485		
	UNITED STATES	OTH	2005/11/15	60/737,532		
	UNITED STATES	OTH	2005/12/9	60/749,247		
	WIPO	CEQ	2006/11/10	PCT/IB2006/003651		
PACKAGE FOR A LIGHT EMITTING ELEMENT WITH INTEGRATED ELECTROSTATIC DISCHARGE PROTECTION						
Thomas Murphy						
	UNITED STATES	NEW	2006/1/20	11/336,094	2009/5/5	7,528,422
	CHINA	DCA	2007/1/16	200780002758.7	2010/2/12	
	EUROPEAN	DCA	2007/1/16	7705678.6		
	HONG KONG	CEQ	2007/1/16	9107474.1		
	JAPAN	DCA	2007/1/16	2008-550873		
	SOUTH KOREA	DCA	2007/1/16	7017700/2008		
	TAIWAN	CEQ	2007/1/19	96101985		
	WIPO	CEQ	2007/1/16	PCT/IB2007/000543		
SMALL FORM FACTOR CAMERA MODULE WITH LENS BARREL AND IMAGE						
Jochen Kuhmann, Andreas Alfred Hase, RALF HAUFFE, Arnd Kilian						
	UNITED STATES	NEW	2006/6/19	11/471,414		
SPACERS FOR WAFER BONDING						
Christoffer Graae Greisen, Lior Shiv, Paul N. Egginton						
	UNITED STATES	NEW	2007/1/8	11/621,045		
	TAIWAN	CEQ	2008/1/7	97100506		
	WIPO	CEQ	2007/12/19	PCT/EP2007/064251		

TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
FORMATION OF THROUGH-WAFER ELECTRICAL INTERCONNECTIONS AND OTHER STRUCTURES USING A THIN DIELECTRIC MEMBRANE						
Lior Shiv						
	UNITED STATES	FCA	2007/1/31	11/669,664	2009/5/12	7,531,445
	UNITED STATES	DIV	2009/4/6	12/418,923	2010/2/16	7,662,710
	UNITED STATES	DIV	2009/9/24	12/566,136	2010/6/8	7,732,240
	CHINA	DCA	2007/9/25	200780035751.5		
	EUROPEAN	DCA	2007/9/25	7849037.2		
	HONG KONG	CEQ	2007/9/25	10101085.2		
	JAPAN	DCA	2007/9/25	2009-529799		
	SOUTH KOREA	DCA	2007/9/25	700607/2009		
	MALAYSIA	DCA	2007/9/25	PI20091216		
	UNITED STATES	NEW	2006/9/26	60/848,043		
	SINGAPORE	DCA	2007/9/25	200901593-4		
	TAIWAN	CEQ	2007/9/21	96135432		
	WIPO	CEQ	2007/9/25	PCT/IB2007/004084		
FABRICATION PROCESS FOR PACKAGE WITH LIGHT EMITTING DEVICE ON A SUB-MOUNT						
Christoffer Graae Greisen, Matthias Heschel, Lior Shiv, Steen Weichel						
	UNITED STATES	NEW	2007/2/15	11/675,179	2010/6/8	7,732,234
	TAIWAN	CEQ	2008/2/14	97105101		
	WIPO	CEQ	2008/1/29	PCT/EP2008/051020		
FABRICATION OF COMPACT SEMICONDUCTOR PACKAGES						
Jochen Kuhmann, Andreas A. Hase						
	UNITED STATES	NEW	2008/1/15	12/014,443		
	TAIWAN	CEQ	2009/1/14	98101150		
	WIPO	CEQ	2008/12/30	PCT/EP2008/068346		
OPTOELECTRONIC DEVICE SUBMOUNT						
Thomas Murphy						
	UNITED STATES	NEW	2008/2/5	12/026,113	2010/6/8	7,732,829
	TAIWAN	CEQ	2009/2/4	98103432		
	WIPO	CEQ	2008/12/30	PCT/EP2008/068347		

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FABRICATION OF COMPACT OPTO-ELECTRONIC COMPONENT PACKAGES						
Jochen Kuhmann						
	UNITED STATES	FCA	2008/9/23	12/236,182		
	UNITED STATES	NEW	2008/6/27	61/076,263		
	TAIWAN	CEQ	2009/6/26	98121495		
	WIPO	CEQ	2009/6/22	PCT/EP2009/057711		
LED PACKAGE WITH REDUCED STAND OFF HEIGHT						
Jorg Rehder						
	UNITED STATES	NEW	2008/7/11	61/079,977		
LED PACKAGE WITH VERTICAL HEAT TRANSFER						
Jorg Rehder, Matthias Heschel						
	UNITED STATES	NEW	2008/7/11	61/079,984		
SOLID-STATE LIGHTING DEVICE PACKAGE WITH SHALLOW CAVITY						
Matthias Heschel, Thomas Murphy						
	UNITED STATES	NEW	2008/9/17	61/097,690		
PACKAGE FOR A LIGHT EMITTING ELEMENT						
Thomas Murphy, Andreas A. Hase, Matthias Heschel						
	UNITED STATES	CIP	2008/10/23	12/257,203		
Silicon-Based Sub-Mount for an Opto-Electronic Device						
Jochen Kuhmann, Heike Huscher						
	UNITED STATES	NEW	2009/2/12	12/369,993		
	TAIWAN	CEQ	2010/2/11	99104248		
	WIPO	CEQ	2010/2/9	PCT/EP2010/051562		
SEMICONDUCTOR-BASED SUBMOUNT WITH ELECTRICALLY CONDUCTIVE FEED-THROUGHS						
Lior Shiv, John Nicholas Shepherd						
	UNITED STATES	FCA	2009/4/27	12/430,591		
	UNITED STATES	NEW	2009/1/14	61/144,525		
	TAIWAN	CEQ	2010/1/12	99100622		
	WIPO	CEQ	2010/1/12	PCT/EP2010/050265		

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TITLE	COUNTRY	TYPE	FILE	SERIALNO	ISSUE	PATENT NO
SEMICONDUCTOR-BASED SUB-MOUNTS FOR OPTOELECTRONIC DEVICES WITH CONDUCTIVE PATHS TO ...						
Christoffer Greisen						
	UNITED STATES	NEW	2009/3/24	12/409,859		
OPTO-ELECTRONIC DEVICE PACKAGE WITH A SEMICONDUCTOR-BASED SUB-MOUNT HAVING SMD						
Jochen Kuhmann, Lior Shiv						
	UNITED STATES	FCA	2009/4/20	12/426,796		
	UNITED STATES	NEW	2009/2/13	61/152,382		
INTEGRATION OF OPTICAL COMPONENTS FOR PACKAGES HOUSING A LIGHT EMITTING DEVICE						
Richard J. Weiss						
	UNITED STATES	NEW	2009/7/15	61/225,648		

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